



## Absolute Maximum Ratings

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The Thermal Resistance and Power Dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition	Min.	Max.	Units	
V <sub>B</sub>	High Side Floating Supply Voltage	-0.3	625	V	
V <sub>S</sub>	High Side Floating Offset Voltage	V <sub>B</sub> - 25	V <sub>B</sub> + 0.3		
V <sub>HO</sub>	High Side Floating Output Voltage	V <sub>S</sub> - 0.3	V <sub>B</sub> + 0.3		
V <sub>CC</sub>	Logic Supply Voltage	-0.3	25		
V <sub>IN</sub>	Logic Input Voltage	-0.3	V <sub>CC</sub> + 0.3		
V <sub>FLT</sub>	FAULT Output Voltage	-0.3	V <sub>CC</sub> + 0.3		
V <sub>CS</sub>	Current Sense Voltage	V <sub>S</sub> - 0.3	V <sub>B</sub> + 0.3		
dV <sub>S</sub> /dt	Allowable Offset Supply Voltage Transient	—	50	V/ns	
P <sub>D</sub>	Package Power Dissipation @ T <sub>A</sub> ≤ +25°C	—	1.0	W	
	(8 Lead SOIC)	—	0.625		
R <sub>THJA</sub>	Thermal Resistance, Junction to Ambient	(8 Lead DIP)	—	125	°C/W
		(8 Lead SOIC)	—	200	
T <sub>J</sub>	Junction Temperature	—	150	°C	
T <sub>S</sub>	Storage Temperature	-55	150		
T <sub>L</sub>	Lead Temperature (Soldering, 10 seconds)	—	300		

## Recommended Operating Conditions

The Input/Output logic timing diagram is shown in Figure 1. For proper operation the device should be used within the recommended conditions. The V<sub>S</sub> offset rating is tested with all supplies biased at 15V differential.

Symbol	Definition	Min.	Max.	Units
V <sub>B</sub>	High Side Floating Supply Voltage	V <sub>S</sub> + 13	V <sub>S</sub> + 20	V
V <sub>S</sub>	High Side Floating Offset Voltage	Note 1	600	
V <sub>HO</sub>	High Side Floating Output Voltage	V <sub>S</sub>	V <sub>B</sub>	
V <sub>CC</sub>	Logic Supply Voltage	13	20	
V <sub>IN</sub>	Logic Input Voltage	0	V <sub>CC</sub>	
V <sub>FLT</sub>	FAULT Output Voltage	0	V <sub>CC</sub>	
V <sub>CS</sub>	Current Sense Signal Voltage	V <sub>S</sub>	V <sub>S</sub> + 5	°C
T <sub>A</sub>	Ambient Temperature	-40	150	

Note 1: Logic operational for V<sub>S</sub> of -5 to +600V. Logic state held for V<sub>S</sub> of -5V to -V<sub>BS</sub>. (Please refer to the Design Tip DT97-3 for more details).

### Dynamic Electrical Characteristics

$V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 15V,  $C_L$  = 1000 pF and  $T_A$  = 25°C unless otherwise specified. The dynamic electrical characteristics are measured using the test circuit shown in Figure 3.

Symbol	Definition	Min.	Typ.	Max.	Units	Test Conditions
$t_{on}$	Turn-On Propagation Delay	—	250	—	ns	$V_S = 0V$
$t_{off}$	Turn-Off Propagation Delay	—	200	—		$V_S = 600V$
$t_r$	Turn-On Rise Time	—	250	—		$C_L = 1000$ pF
$t_f$	Turn-Off Fall Time	—	250	—		$C_L = 1000$ pF
$t_{bl}$	Start-Up Blanking Time	500	900	—		
$t_{cs}$	CS Shutdown Propagation Delay	—	350	—		
$t_{fit}$	CS to $\overline{FAULT}$ Pull-Up Propagation Delay	—	450	—		

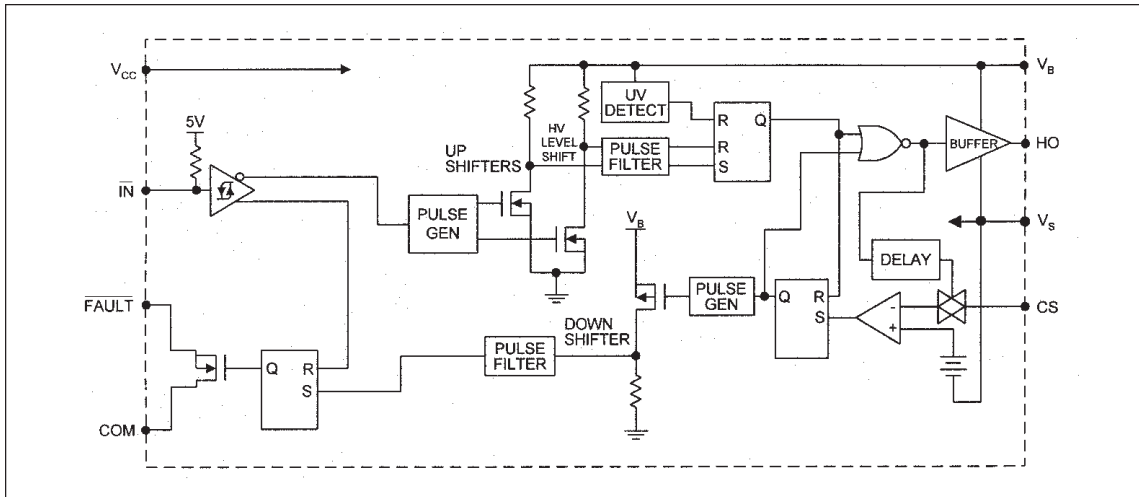
### Static Electrical Characteristics

$V_{BIAS}$  ( $V_{CC}$ ,  $V_{BS}$ ) = 15V and  $T_A$  = 25°C unless otherwise specified. The  $V_{IN}$ ,  $V_{TH}$  and  $I_{IN}$  parameters are referenced to COM. The  $V_O$  and  $I_O$  parameters are referenced to  $V_S$ .

Symbol	Definition	Min.	Typ.	Max.	Units	Test Conditions
$V_{IH}$	Logic "0" Input Voltage (OUT = LO)	3.0	—	—	V	$V_{CC} = 10V$ to 20V
$V_{IL}$	Logic "1" Input Voltage (OUT = HI)	—	—	0.8		$V_{CC} = 10V$ to 20V
$V_{CSTH+}$	CS Input Positive Going Threshold	350	500	650	mV	$V_{CC} = 10V$ to 20V
$V_{OH}$	High Level Output Voltage, $V_{BIAS} - V_O$	—	—	100		$I_O = 0A$
$V_{OL}$	Low Level Output Voltage, $V_O$	—	—	100		$I_O = 0A$
$I_{LK}$	Offset Supply Leakage Current	—	—	50	$\mu A$	$V_B = V_S = 600V$
$I_{QBS}$	Quiescent $V_{BS}$ Supply Current	—	150	350		$V_{IN} = 0V$ or 5V
$I_{QCC}$	Quiescent $V_{CC}$ Supply Current	—	60	120		$V_{IN} = 0V$ or 5V
$I_{IN+}$	Logic "1" Input Bias Current	—	7.0	15		$V_{IN} = 0V$
$I_{IN-}$	Logic "0" Input Bias Current	—	—	1.0		$V_{IN} = 5V$
$I_{CS+}$	"High" CS Bias Current	—	—	1.0		$V_{CS} = 3V$
$I_{CS-}$	"High" CS Bias Current	—	—	1.0		$V_{CS} = 0V$
$V_{BSUV+}$	$V_{BS}$ Supply Undervoltage Positive Going Threshold	10.0	11.4	13.0	V	
$V_{BSUV-}$	$V_{BS}$ Supply Undervoltage Negative Going Threshold	9.5	10.4	12.5		
$I_{O+}$	Output High Short Circuit Pulsed Current	110	130	—	mA	$V_O = 0V$ , $V_{IN} = 0V$ PW $\leq 10$ $\mu s$
$I_{O-}$	Output Low Short Circuit Pulsed Current	110	130	—		$V_O = 15V$ , $V_{IN} = 5V$ PW $\leq 10$ $\mu s$

# IR2122(S)

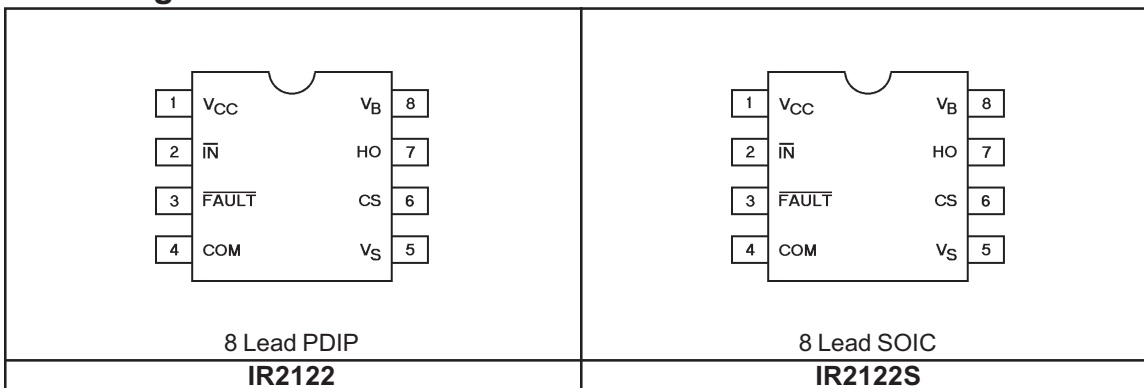
## Functional Block Diagram



## Lead Definitions

Symbol	Description
V <sub>CC</sub>	Logic and gate drive supply
I <sub>N</sub>	Logic input for gate driver output (HO), out of phase with HO
FAULT	Indicates over-current shutdown has occurred, negative logic
COM	Logic ground
V <sub>B</sub>	High side floating supply
HO	High side gate drive output
V <sub>S</sub>	High side floating supply return
CS	Current sense input to current sense comparator

## Lead Assignments



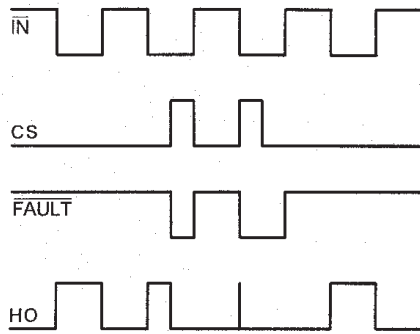


Figure 1. Input/Output Timing Diagram

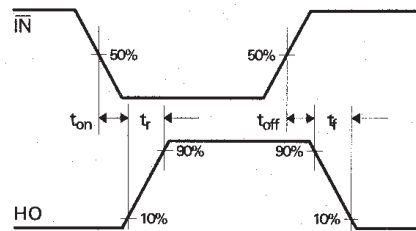


Figure 2. Switching Time Waveform Definition

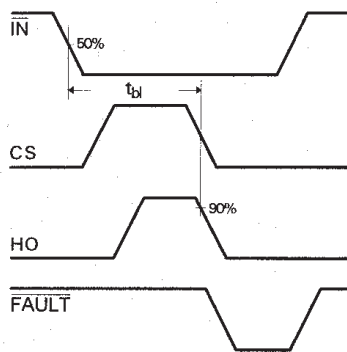


Figure 3. Start-up Blanking Time Waveform Definitions

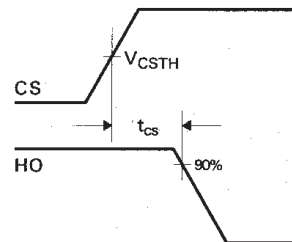


Figure 4. CS Shutdown Waveform Definitions

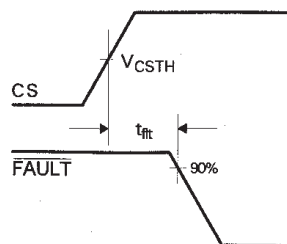


Figure 5. CS to  $\overline{\text{FAULT}}$  Waveform Definitions

# IR2122(S)

## Case outlines

**8-Lead PDIP**

01-6014  
01-3003 01 (MS-001AB)

**NOTES:**

1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M-1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-001AB.
- ⑤ MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM PLANE C.
- ⑥ DIMENSION DOES NOT INCLUDE MOLD PROTUSIONS. MOLD PROTUSIONS SHALL NOT EXCEED 0.25 [.010].

**8-Lead SOIC**

01-6027  
01-0021 11 (MS-012AA)

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°

**NOTES:**

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
- ⑤ DIMENSION DOES NOT INCLUDE MOLD PROTUSIONS. MOLD PROTUSIONS NOT TO EXCEED 0.15 [.006].
- ⑥ DIMENSION DOES NOT INCLUDE MOLD PROTUSIONS. MOLD PROTUSIONS NOT TO EXCEED 0.25 [.010].
- ⑦ DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245 Tel: (310) 252-7105  
Data and specifications subject to change without notice. 2/2/2005